## SN54AHCT16244, SN74AHCT16244 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCLS334I - MARCH 1996 - REVISED JANUARY 2000

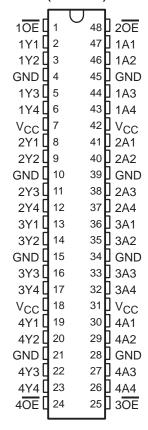
- Members of the Texas Instruments Widebus™ Family
- EPIC<sup>™</sup> (Enhanced-Performance Implanted CMOS) Process
- Inputs Are TTL-Voltage Compatible
- Distributed V<sub>CC</sub> and GND Pins Minimize High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015
- Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

#### description

The 'AHCT16244 devices are 16-bit buffers and line drivers designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

These devices can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. They provide true outputs and symmetrical active-low output-enable (OE) inputs.

SN54AHCT16244 . . . WD PACKAGE SN74AHCT16244 . . . DGG, DGV, OR DL PACKAGE (TOP VIEW)



To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54AHCT16244 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74AHCT16244 is characterized for operation from –40°C to 85°C.

## FUNCTION TABLE (each 4-bit buffer/driver)

INPU	JTS	OUTPUT
OE	Α	Υ
L	Н	Н
L	L	L
Н	Χ	Z



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

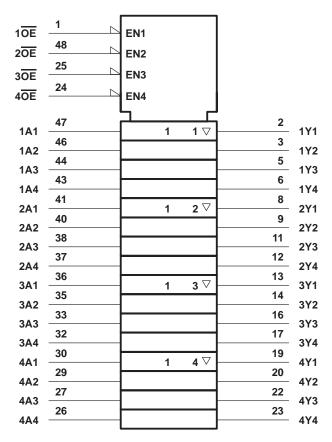
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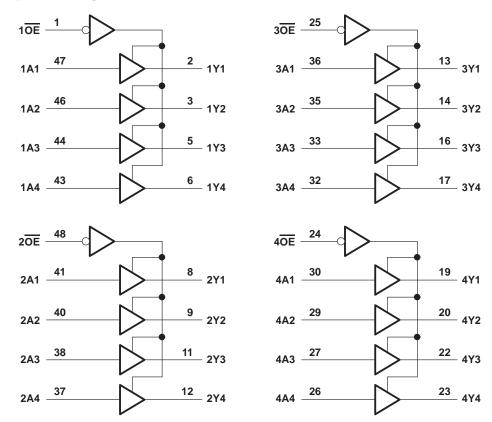
## logic symbol†



 $<sup>\</sup>ensuremath{^{\dagger}}$  This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



#### logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$
DL package

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51.



## SN54AHCT16244, SN74AHCT16244 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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### recommended operating conditions (see Note 3)

		SN54AHC	T16244	SN74AHC	T16244	UNIT
		MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	2	2		V
V <sub>IL</sub>	Low-level input voltage		8.0		0.8	V
٧ı	Input voltage	0 4	5.5	0	5.5	V
Vo	Output voltage	0	VCC	0	Vcc	V
IOH	High-level output current	2	-8		-8	mA
l <sub>OL</sub>	Low-level output current	20%	8		8	mA
Δt/Δν	Input transition rise or fall rate	Q	20		20	ns/V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vaa	T <sub>A</sub> = 25°C			SN54AHCT16244		SN74AHCT16244		UNIT
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
Vall	I <sub>OH</sub> = -50 μA	4.5 V	4.4	4.5		4.4		4.4		V
VOH	$I_{OH} = -8 \text{ mA}$	4.5 V	3.94			3.8		3.8		V
Vol	I <sub>OL</sub> = 50 μA	4.5 V			0.1		0.1		0.1	V
VOL	$I_{OL} = 8 \text{ mA}$	4.5 V			0.36		0.44		0.44	ı v
IĮ	$V_I = V_{CC}$ or GND	0 V to 5.5 V			±0.1	5	±1*		±1	μΑ
loz	$V_O = V_{CC}$ or GND	5.5 V			±0.25	1	±2.5		±2.5	μΑ
lcc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			4	25	40		40	μΑ
∆l <sub>CC</sub> †	One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	5.5 V			1.35	PRO1	1.5		1.5	mA
Ci	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		2.5	10				10	pF
Co	$V_O = V_{CC}$ or GND	5 V		3						pF

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter is not production tested at V<sub>CC</sub> = 0 V.

<sup>†</sup>This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or VCC.

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# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T	λ = 25°C	;	SN54AHC	T16244	SN74AHC	T16244	UNIT			
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT			
t <sub>PLH</sub>	А	Υ	C <sub>I</sub> = 15 pF		5.4*	8.5*	1*	10*	1	9.5	ns			
t <sub>PHL</sub>	ζ	ı	CL = 13 pr		5.4*	8.5*	1*	10*	1	9.5	115			
<sup>t</sup> PZH	ŌĒ	Y	C 15 pE		7.7*	10.4*	1*	12*	1	12	ns			
tPZL	OE	ı	C <sub>L</sub> = 15 pF		7.7*	10.4*	1*	12*	1	12	115			
t <sub>PHZ</sub>	ŌĒ	Y	C 15 pE		5*	10.4*	1*	12*	1	12	ns			
t <sub>PLZ</sub>	OL	'	C <sub>L</sub> = 15 pF		5*	10.4*	1*0	12*	1	12	115			
tPLH	Α		V	Υ	V	C: 50 pF		7	9.5	9	11	1	10.5	ns
tPHL	χ.	Ĭ	C <sub>L</sub> = 50 pF		5.9	9.5	Q <sup>1</sup>	11	1	10.5	115			
t <sub>PZH</sub>	ŌĒ	Y	C 50 pE		8.2	11.4	2 1	13	1	13	no			
tPZL	OE	Ĭ	$C_L = 50 pF$		8.2	11.4	1	13	1	13	ns			
t <sub>PHZ</sub>	ŌĒ	Y Cı	C 50 pE		8.8	11.4	1	13	1	13				
t <sub>PLZ</sub>	OE	ı ı	$C_L = 50 \text{ pF}$		8.8	11.4	1	13	1	13	ns			
tsk(o)			C <sub>L</sub> = 50 pF			1**				1	ns			

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter is not production tested.

## noise characteristics, $V_{CC} = 5 \text{ V}$ , $C_L = 50 \text{ pF}$ , $T_A = 25^{\circ}\text{C}$ (see Note 4)

	PARAMETER	SN74	UNIT		
	PARAMETER	MIN	TYP	MAX	UNIT
V <sub>OL(P)</sub>	Quiet output, maximum dynamic VOL		0.7		V
V <sub>OL(V)</sub>	Quiet output, minimum dynamic V <sub>OL</sub>		-0.7		V
V <sub>OH(V)</sub>	Quiet output, minimum dynamic V <sub>OH</sub>		4.8		V
VIH(D)	High-level dynamic input voltage	2			V
V <sub>IL(D)</sub>	Low-level dynamic input voltage			0.8	V

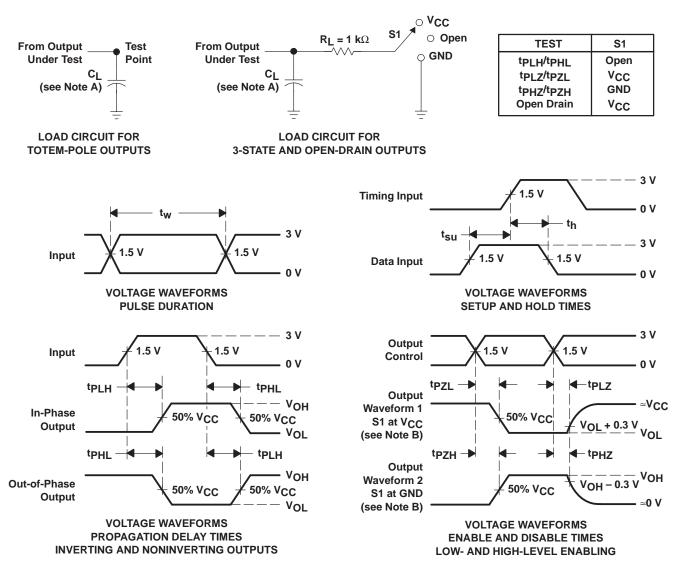
NOTE 4: Characteristics are for surface-mount packages only.

### operating characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST C	ONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load,	f = 1 MHz	8.2	pF

<sup>\*\*</sup> On products compliant to MIL-PRF-38535, this parameter does not apply.

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq 3$  ns,  $t_f \leq 3$  ns.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







com 18-Sep-2008

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74AHCT16244DGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHCT16244DGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHCT16244DGVRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHCT16244DGVRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHCT16244DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT16244DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT16244DGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT16244DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT16244DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT16244DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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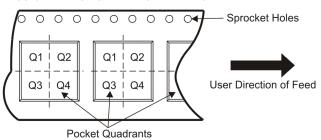
#### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCT16244DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74AHCT16244DGVR	TVSOP	DGV	48	2000	330.0	24.4	6.8	10.1	1.6	12.0	24.0	Q1
SN74AHCT16244DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1





\*All dimensions are nominal

7 til dillionolollo alo nominal							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCT16244DGGR	TSSOP	DGG	48	2000	346.0	346.0	41.0
SN74AHCT16244DGVR	TVSOP	DGV	48	2000	346.0	346.0	41.0
SN74AHCT16244DLR	SSOP	DL	48	1000	346.0	346.0	49.0

### DGG (R-PDSO-G\*\*)

### PLASTIC SMALL-OUTLINE PACKAGE

#### **48 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

#### DL (R-PDSO-G\*\*)

#### **48 PINS SHOWN**

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

### DGV (R-PDSO-G\*\*)

#### **24 PINS SHOWN**

#### **PLASTIC SMALL-OUTLINE**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

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